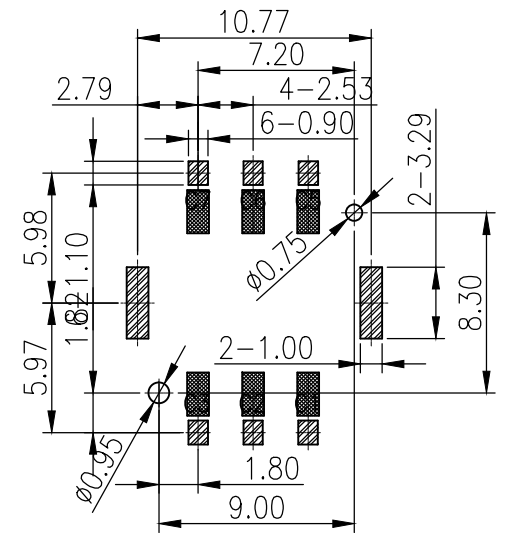
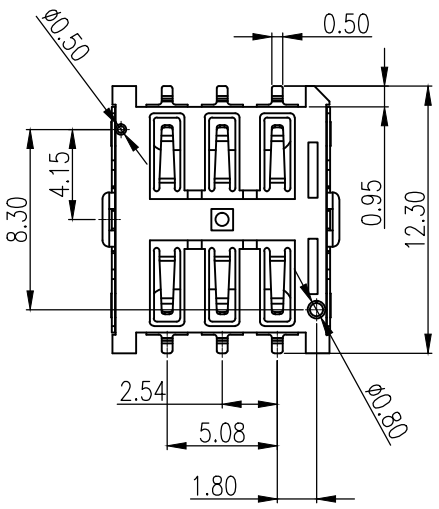
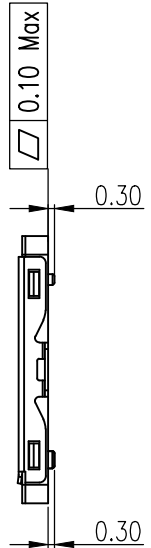
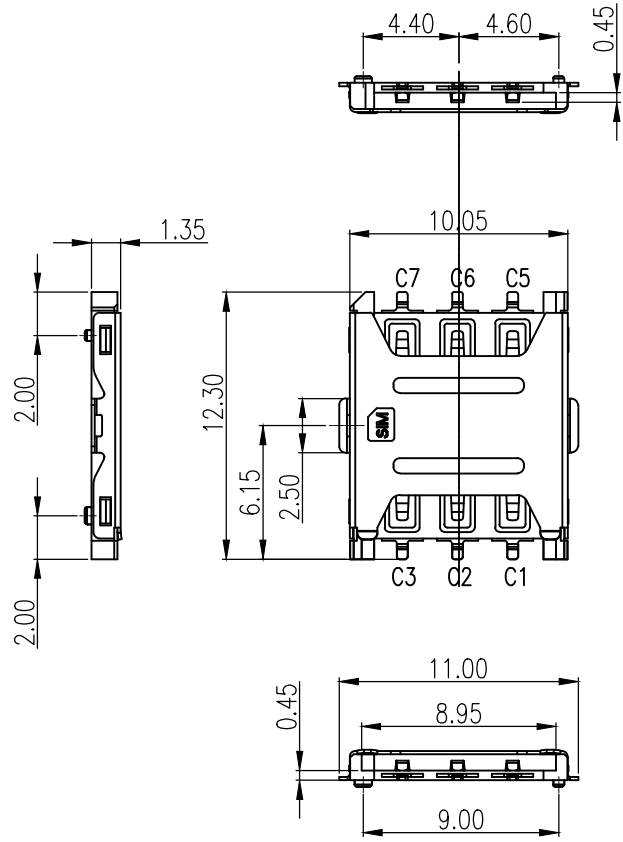
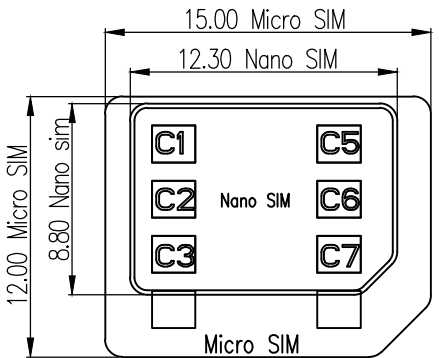


RoHS

| REV. | EC# | DESCRIPTION | DATE | DRAWING | CHECKED | APPROVED |
|------|-----|-------------|------|---------|---------|----------|
| | | | | | | |
| | | | | | | |



RECOMMENDED PCB LAYOUT
 PATTERN PROHIBITION AREA



| SIM pin assignment | |
|--------------------|---------|
| PIN# | Name |
| C1 | VCC供电电压 |
| C2 | RST重置 |
| C3 | CLK时钟 |
| C5 | GND接地 |
| C6 | VPP程序电压 |
| C7 | I/O输入输出 |

- NOTES:
- MATERIAL:
 - Insulator: High Temperature Thermoplastic, UL94V-0; Color Black.
 - Terminal: Copper Alloy.
 - Shell: Stainless Steel.
 - PLATING:
 - Contact: Plated 50u" Ni Overall Contact Au 1u",
 - Shell: Plated 50u" Ni Overall, PAD Au 1u"
 - SPECIALITY:
 - Current Rating :0.5mA AC/DC max.
 - Voltage Rating :125V AC/DC
 - Ambient Temperature Range :-20° C+60° C
 - Storage Temperature Range :-40° C+70° C
 - Ambient Humidity Range :95% R.H. Max.
 - Contact Resistance:100mΩ max.
 - Insulation Resistance:1000MΩ min./500VDC
 - Mating Cycles:10,000 Insertions
 - Reflow peak temp.: 260° C ±5° C, 3~5 S
 - Mating Cycles:3,000 Insertions Min
 - PLEASE CONTACT LQ SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY

| | | | | | | | | |
|---|-------|----------|-----------------|----------------|-------|--------|-----|--------|
| Unless otherwise specified tolerances are | | | | | | | | |
| X.X | ±0.30 | | | | | | | |
| X.XX | ±0.20 | DRAW NO. | DATE | DRAW NAME: | | | | |
| X.XXX | ±0.10 | DWN | | 拔插式 NanoSIM卡卡座 | | | | |
| X' | ±3.0' | CHK | | P/N : | | | | |
| X.X' | ±1.5' | APVD | | | | | | |
| Third Angle Project | | FINISH | | UNIT | SCALE | WEIGHT | REV | SHEET |
| | | DWG NO. | BX-SMN-1.35HJ-C | mm | 1:1 | | A0 | 1 OF 2 |